

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Heisley	Docket No.: TI-33886.1
Serial No.: TBD	Examiner: TBD
Filed: 3/2/2004	Art Unit: TBD
For: WAFER ALIGNMENT DEVICE AND METHOD	

PRELIMINARY AMENDMENT

Honorable Assistant Commissioner
of Patents
Washington, D.C. 20231

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Date of Deposit: 3-2-04

Prior to the examination of the above identified application, please amend the above referenced Application as follows:

TI-33886.1